



PLASTIC TECHNOLOGIES, INC.



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LAS VEGAS, NV Feb. 5, 2008 “The Packaging Conference 2008”.

SACMI Premieres Preform Advanced Molding Technology at The Packaging Conference

Sacmi Imola unveiled the details of a new preform molding platform at The Packaging Conference being held at the MGM Grand in Las Vegas, Nevada. Luca Nanetti announced that Sacmi has developed the first commercially available compression molding machine for preform production. The first machine will be a 48 cavity wheel with a post cooling option to produce 450 preforms per minute. The preform being produced is for a single service water package. Sacmi is working to develop manufacturing equipment able to respond to other markets such as carbonated, hot fill, wide-mouth and light weight packages.

The Preform Advanced Molding, or PAM, compression process offers several advantages over conventional injection molding. The melt flow path has no branching and minimal residence time which minimizes both melt temperature and polymer degradation. The resulting preform also does not have a gate vestige which is inherent in the injection molding process. The elimination of the vestige can improve bottle bases for pressure performance. The melt flow in the cavity also provides more freedom to minimize thickness in the end cap and design lighter weight preforms. Since PAM is a continuous process the preforms are handled in a linear fashion which reduces damage and can facilitate linking the machine with blowing and filling equipment in the future.

According to SACMI the machine will become available in early 2009.

For more information please contact:

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